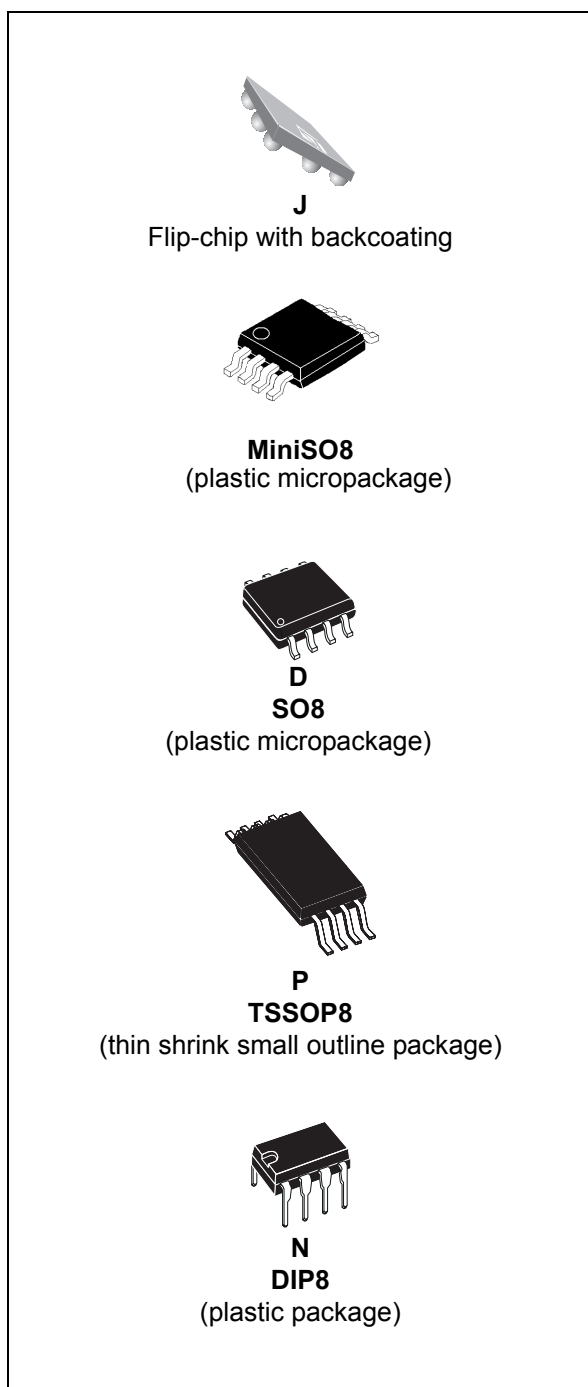


Rail-to-rail, high output current dual operational amplifier

Datasheet - production data

**Features**

- Rail-to-rail input and output
- Low noise: $9 \text{ nV}/\sqrt{\text{Hz}}$
- Low distortion
- High output current: 80 mA (able to drive 32Ω loads)
- High-speed: 4 MHz, $1 \text{ V}/\mu\text{s}$
- Operating from 2.7 to 12 V
- Low input offset voltage: 900 μV max. (TS922A)
- ESD internal protection: 2 kV
- Latch-up immunity
- Macromodel included in this specification
- Dual version available in Flip-chip package

Applications

- Headphone and servo amplifiers
- Sound cards, multimedia systems
- Line drivers, actuator drivers
- Mobile phones and portable equipment
- Instrumentation with low noise as key factor
- Piezoelectric speaker drivers

Description

TS922 and TS922A devices are rail-to-rail dual BiCMOS operational amplifiers optimized and fully specified for 3 V and 5 V operation. These devices have high output currents which allow low-load impedances to be driven.

Very low noise, low distortion, low offset, and a high output current capability make these devices an excellent choice for high quality, low voltage, or battery operated audio systems.

The devices are stable for capacitive loads up to 500 pF

Contents

- 1 Pin diagrams 3**
- 2 Absolute maximum ratings and operating conditions 4**
- 3 Electrical characteristics 6**
- 4 TS922, TS922A macromodel 12**
 - 4.1 Important note concerning this macromodel 12
 - 4.2 Electrical characteristics from macromodelization 12
 - 4.3 Macromodel code 13
- 5 Package information 15**
 - 5.1 8-bump Flip-chip package information 16
 - 5.2 MiniSO8 package information 18
 - 5.3 SO8 package information 19
 - 5.4 TSSOP8 package information 20
 - 5.5 DIP8 package information 21
- 6 Ordering information 22**
- 7 Revision history 23**

1 Pin diagrams

Figure 1. Pinout for Flip-chip package (top view)

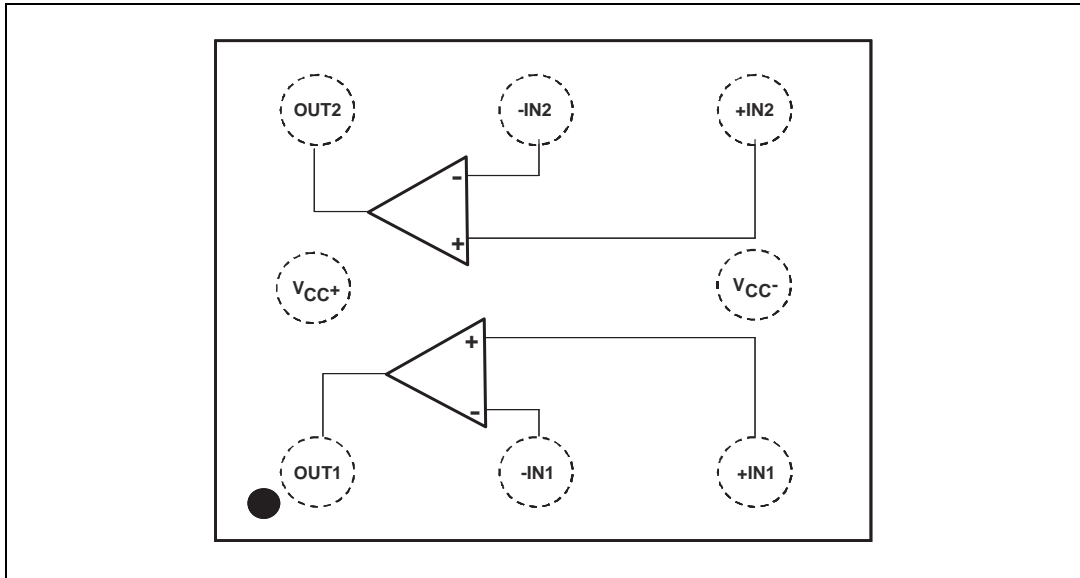
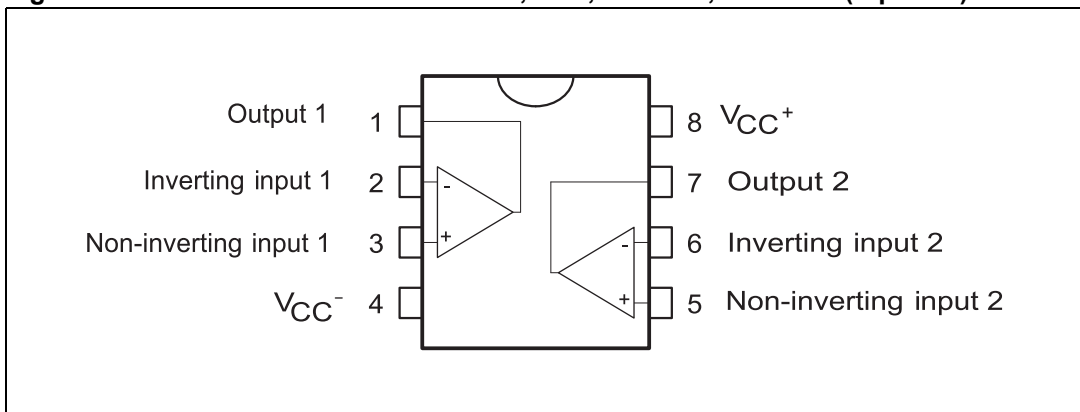


Figure 2. Pin connections for MiniSO8, SO8, TSSOP8, and DIP8 (top view)



2 Absolute maximum ratings and operating conditions

Table 1. Absolute maximum ratings (AMR)

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage ⁽¹⁾	14	V
V_{id}	Differential input voltage ⁽²⁾	± 1	
V_{in}	Input voltage ⁽³⁾	$V_{CC} - 0.3$ to $V_{CC} + 0.3$	
T_{stg}	Storage temperature	-65 to +150	°C
R_{thja}	Thermal resistance junction to ambient ⁽⁴⁾		°C/W
	Flip-chip	90	
	SO8	125	
	TSSOP8	120	
R_{thjc}	Thermal resistance junction to case ⁽⁴⁾		
	SO8	40	
	TSSOP8	37	
T_j	Maximum junction temperature	150	°C
ESD	HBM: human body model ⁽⁵⁾	2000	V
	MM: machine model ⁽⁶⁾	120	
	CDM: charged device model ⁽⁷⁾	1500	
	Output short-circuit duration	See note ⁽⁸⁾	
	Latch-up immunity	200	mA
	Soldering temperature (10 s), leaded version	250	°C
	Soldering temperature (10 s), unleaded version	260	

1. All voltage values, except differential voltage are with respect to network ground terminal.
2. The differential voltage is the non-inverting input terminal with respect to the inverting input terminal. If $V_{id} > \pm 1$ V, the maximum input current must not exceed ± 1 mA. In this case ($V_{id} > \pm 1$ V), an input series resistor must be added to limit the input current.
3. Do not exceed 14 V.
4. Short-circuits can cause excessive heating. Destructive dissipation can result from simultaneous short-circuits on all amplifiers. These values are typical.
5. Human body model: 100 pF discharged through a 1.5 kΩ resistor between two pins of the device, done for all couples of pin combinations with other pins floating.
6. Machine model: a 200 pF capacitor is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5 Ω). This is done for all couples of pin combinations with other pins floating.
7. Charged device model: all pins and plus package are charged together to the specified voltage and then discharged directly to ground.
8. There is no short-circuit protection inside the device: short-circuits from the output to V_{CC} can cause excessive heating. The maximum output current is approximately 80 mA, independent of the magnitude of V_{CC} . Destructive dissipation can result from simultaneous short-circuits on all amplifiers.

Table 2. Operating conditions

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	2.7 to 12	V
V_{icm}	Common mode input voltage range	$V_{CC} - 0.2$ to $V_{CC} + 0.2$	
T_{oper}	Operating free air temperature range	-40 to +125	°C

3 Electrical characteristics

Table 3. Electrical characteristics measured at $V_{CC} = +3\text{ V}$, $V_{CC-} = 0\text{ V}$, $V_{icm} = V_{CC}/2$, $T_{amb} = 25\text{ °C}$, and R_L connected to $V_{CC}/2$ (unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{io}	Input offset voltage	TS922 TS922A TS922IJ (Flip-chip)			3 0.9 1.5	mV
		$T_{min} \leq T_{amb} \leq T_{max}$ TS922 TS922A TS922IJ (Flip-chip)			5 1.8 2.5	
$\Delta V_{io}/\Delta T$	Input offset voltage drift			2		$\mu\text{V}/\text{°C}$
I_{io}	Input offset current	$V_{out} = V_{CC}/2$ $T_{min} \leq T_{amb} \leq T_{max}$		1	30 30	nA
I_{ib}	Input bias current	$V_{out} = V_{CC}/2$ $T_{min} \leq T_{amb} \leq T_{max}$		15	100 100	
V_{OH}	High level output voltage	$R_L = 10\text{ k}\Omega$ $T_{min} \leq T_{amb} \leq T_{max}$	2.90 2.90			V
		$R_L = 600\ \Omega$ $T_{min} \leq T_{amb} \leq T_{max}$	2.87 2.87			
		$R_L = 32\ \Omega$		2.63		
V_{OL}	Low level output voltage	$R_L = 10\text{ k}\Omega$ $T_{min} \leq T_{amb} \leq T_{max}$			50 50	mV
		$R_L = 600\ \Omega$ $T_{min} \leq T_{amb} \leq T_{max}$			100 100	
		$R_L = 32\ \Omega$		180		
A_{vd}	Large signal voltage gain	$R_L = 10\text{ k}\Omega$, $V_{out} = 2\text{ V}_{p-p}$ $T_{min} \leq T_{amb} \leq T_{max}$	70	200		V/mV
		$R_L = 600\ \Omega$, $V_{out} = 2\text{ V}_{p-p}$ $T_{min} \leq T_{amb} \leq T_{max}$	15	35		
		$R_L = 32\ \Omega$, $V_{out} = 2\text{ V}_{p-p}$		16		
I_{CC}	Total supply current	No load, $V_{out} = V_{CC}/2$ $T_{min} \leq T_{amb} \leq T_{max}$		2	3 3.2	mA
GBP	Gain bandwidth product	$R_L = 600\ \Omega$		4		MHz
CMR	Common mode rejection ratio	$V_{icm} = 0\text{ to }3\text{ V}$ $T_{min} \leq T_{amb} \leq T_{max}$	60 56	80		dB
SVR	Supply voltage rejection ratio	$V_{CC} = 2.7\text{ to }3.3\text{ V}$ $T_{min} \leq T_{amb} \leq T_{max}$	60 60	85		
I_o	Output short-circuit current		50	80		mA
SR	Slew rate		0.7	1.3		V/ μs

Table 3. Electrical characteristics measured at $V_{CC} = +3\text{ V}$, $V_{CC-} = 0\text{ V}$, $V_{icm} = V_{CC}/2$, $T_{amb} = 25\text{ °C}$, and R_L connected to $V_{CC}/2$ (unless otherwise specified) (continued)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
ϕ_m	Phase margin at unit gain	$R_L = 600\ \Omega$, $C_L = 100\text{ pF}$		68		Degrees
G_m	Gain margin			12		dB
e_n	Equivalent input noise voltage	$f = 1\text{ kHz}$		9		$\frac{nV}{\sqrt{Hz}}$
THD	Total harmonic distortion	$V_{out} = 2\text{ V}_{p-p}$, $f = 1\text{ kHz}$, $A_v = 1$, $R_L = 600\ \Omega$		0.005		%
C_s	Channel separation			120		dB

Table 4. Electrical characteristics measured at $V_{CC} = 5\text{ V}$, $V_{CC-} = 0\text{ V}$, $V_{icm} = V_{CC}/2$, $T_{amb} = 25\text{ }^{\circ}\text{C}$, and R_L connected to $V_{CC}/2$ (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V_{io}	Input offset voltage	TS922 TS922A TS922IJ (Flip-chip)			3 0.9 1.5	mV
		$T_{min} \leq T_{amb} \leq T_{max}$ TS922 TS922A TS922IJ (Flip-chip)			5 1.8 2.5	
$\Delta V_{io}/\Delta T$	Input offset voltage drift			2		$\mu\text{V}/^{\circ}\text{C}$
I_{io}	Input offset current	$V_{out} = V_{CC}/2$ $T_{min} \leq T_{amb} \leq T_{max}$		1	30 30	nA
I_{ib}	Input bias current	$V_{out} = V_{CC}/2$ $T_{min} \leq T_{amb} \leq T_{max}$		15	100 100	
V_{OH}	High level output voltage	$R_L = 10\text{ k}\Omega$ $T_{min} \leq T_{amb} \leq T_{max}$	4.9 4.9			V
		$R_L = 600\ \Omega$ $T_{min} \leq T_{amb} \leq T_{max}$	4.85 4.85			
		$R_L = 32\ \Omega$		4.4		
V_{OL}	Low level output voltage	$R_L = 10\text{ k}\Omega$ $T_{min} \leq T_{amb} \leq T_{max}$			50 50	mV
		$R_L = 600\ \Omega$ $T_{min} \leq T_{amb} \leq T_{max}$			120 120	
		$R_L = 32\ \Omega$		300		
A_{vd}	Large signal voltage gain	$R_L = 10\text{ k}\Omega$, $V_{out} = 2\text{ V}_{p-p}$ $T_{min} \leq T_{amb} \leq T_{max}$	70	200		V/mV
		$R_L = 600\ \Omega$, $V_{out} = 2\text{ V}_{p-p}$ $T_{min} \leq T_{amb} \leq T_{max}$	20	35		
		$R_L = 32\ \Omega$, $V_{out} = 2\text{ V}_{p-p}$		16		
I_{cc}	Total supply current	No load, $V_{out} = V_{CC}/2$ $T_{min} \leq T_{amb} \leq T_{max}$		2	3 3.2	mA
GBP	Gain bandwidth product	$R_L = 600\ \Omega$		4		MHz
CMR	Common mode rejection ratio	$V_{icm} = 0\text{ to }5\text{ V}$ $T_{min} \leq T_{amb} \leq T_{max}$	60 56	80		dB
SVR	Supply voltage rejection ratio	$V_{CC} = 4.5\text{ to }5.5\text{ V}$ $T_{min} \leq T_{amb} \leq T_{max}$	60 60	85		
I_o	Output short-circuit current		50	80		mA
SR	Slew rate		0.7	1.3		V/ μs
ϕ_m	Phase margin at unit gain	$R_L = 600\ \Omega$, $C_L = 100\text{ pF}$		68		Degrees
G_m	Gain margin			12		dB
e_n	Equivalent input noise voltage	$f = 1\text{ kHz}$		9		$\frac{\text{nV}}{\sqrt{\text{Hz}}}$

Table 4. Electrical characteristics measured at $V_{CC} = 5\text{ V}$, $V_{CC-} = 0\text{ V}$, $V_{icm} = V_{CC}/2$, $T_{amb} = 25\text{ °C}$, and R_L connected to $V_{CC}/2$ (unless otherwise specified) (continued)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
THD	Total harmonic distortion	$V_{out} = 2 V_{p-p}$, $f = 1\text{ kHz}$, $A_v = 1$, $R_L = 600\ \Omega$		0.005		%
C_s	Channel separation			120		dB

Figure 3. Output short-circuit current vs. output voltage

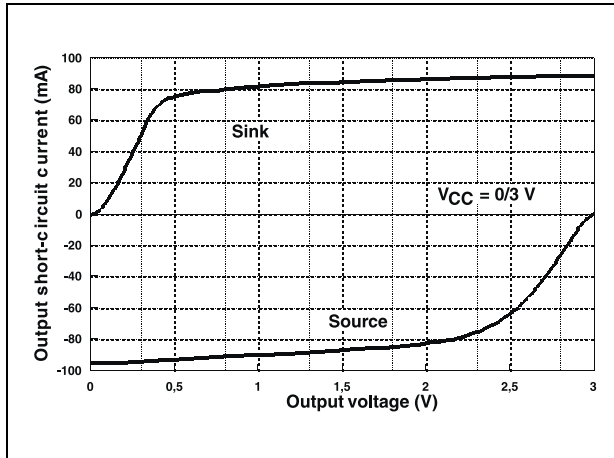


Figure 4. Total supply current vs. supply voltage

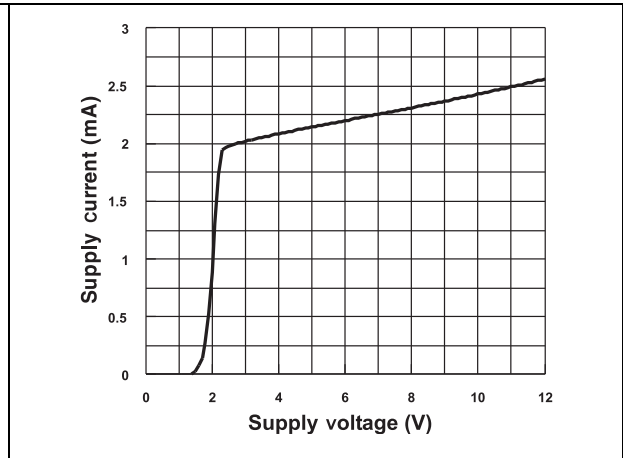


Figure 5. Voltage gain and phase vs. frequency

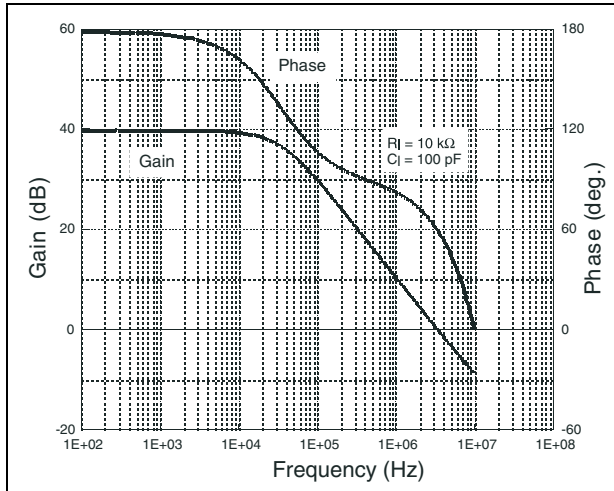


Figure 6. Equivalent input noise voltage vs. frequency

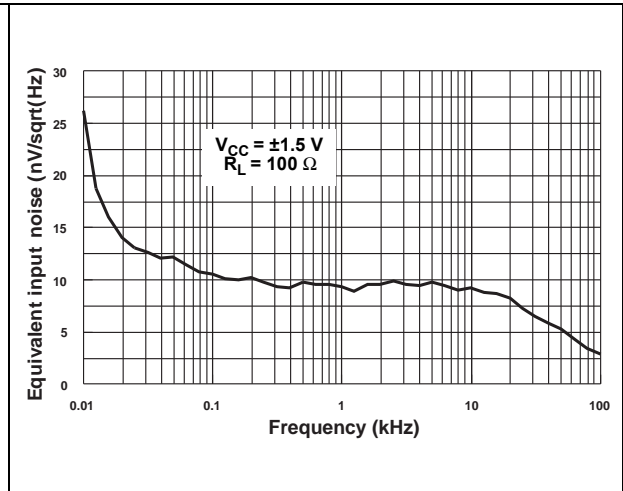


Figure 7. THD + noise vs. frequency (RL = 2 kΩ, Vo = 10 Vpp, VCC = ± 6 V)

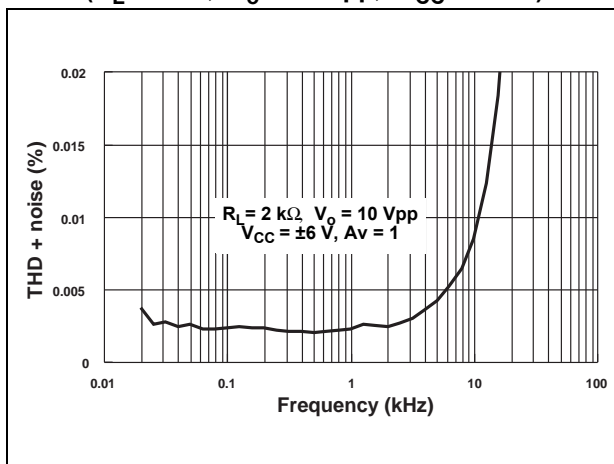


Figure 8. THD + noise vs. frequency (RL = 32 Ω, Vo = 4 Vpp, VCC = ± 2.5 V)

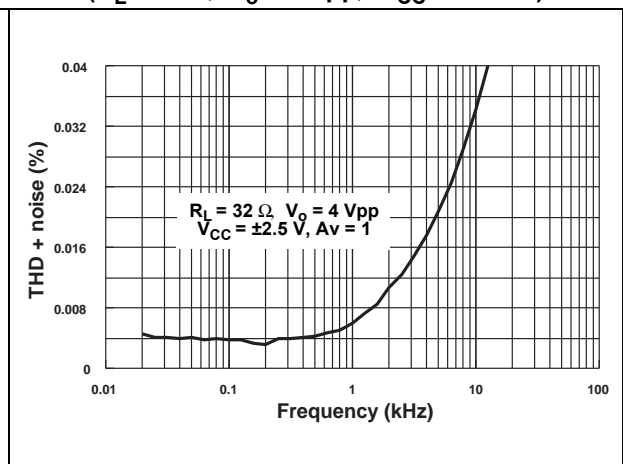


Figure 9. THD + noise vs. frequency
 ($R_L = 32 \Omega$, $V_o = 2 V_{pp}$, $V_{CC} = \pm 1.5 V$)

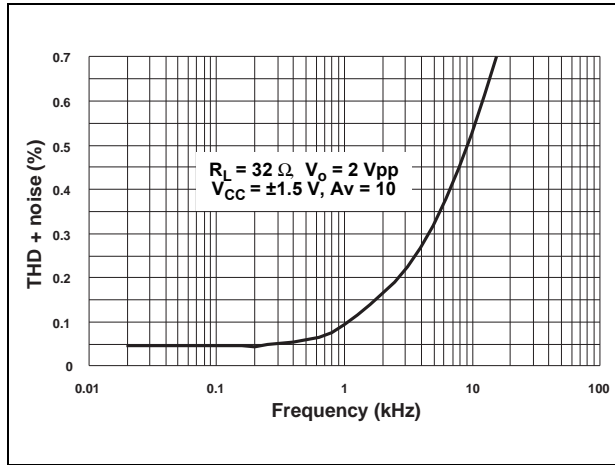


Figure 10. THD + noise vs. output voltage
 ($R_L = 600 \Omega$, $f = 1 kHz$, $V_{CC} = 0/3 V$)

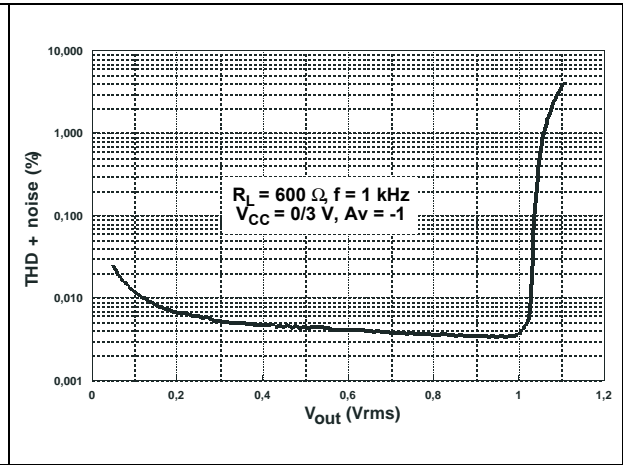


Figure 11. THD + noise vs. output voltage
 ($R_L = 32 \Omega$, $f = 1 kHz$, $V_{CC} = \pm 1.5 V$)

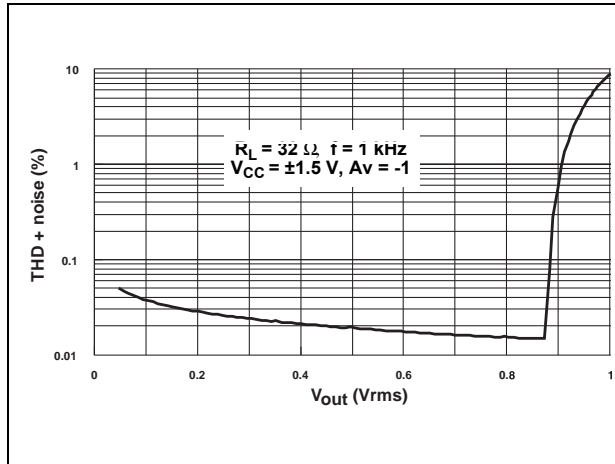


Figure 12. THD + noise vs. output voltage
 ($R_L = 2 k\Omega$, $f = 1 kHz$, $V_{CC} = \pm 1.5 V$)

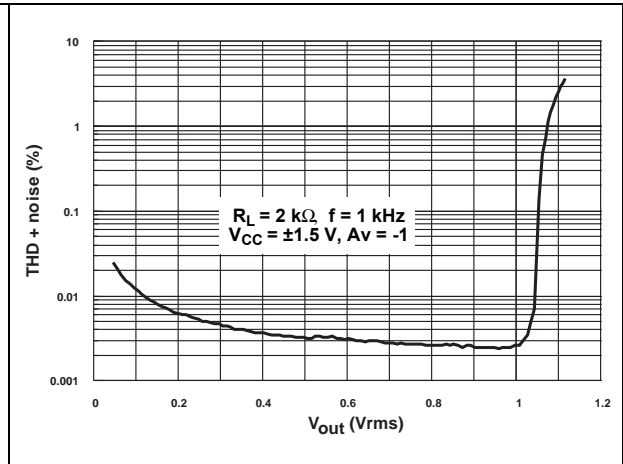
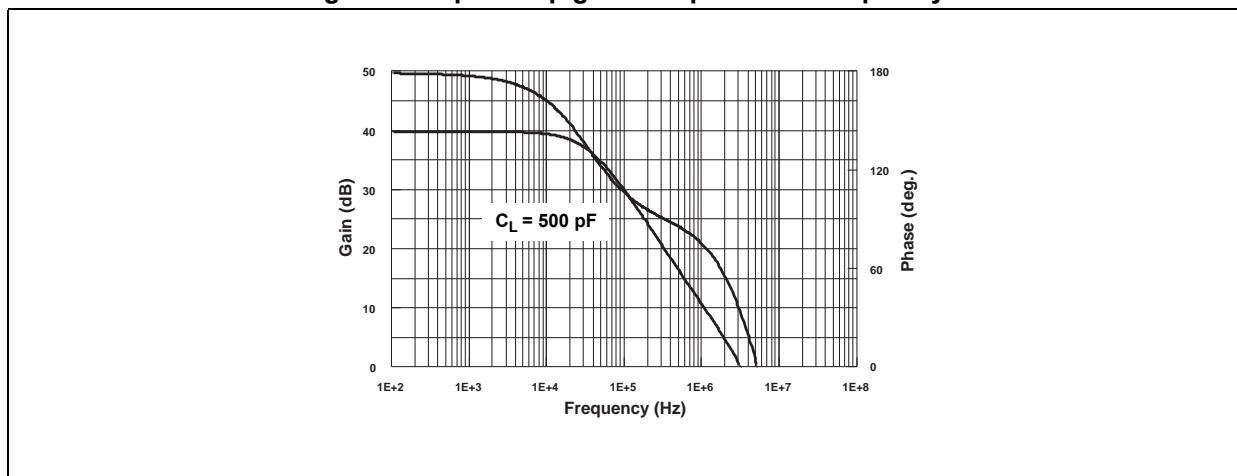


Figure 13. Open loop gain and phase vs. frequency



4 TS922, TS922A macromodel

4.1 Important note concerning this macromodel

- All models are a trade-off between accuracy and complexity (i.e. simulation time).
- Macromodels are not a substitute to breadboarding; rather, they confirm the validity of a design approach and help to select surrounding component values.
- A macromodel emulates the **nominal** performance of a **typical** device within **specified operating conditions** (for example, temperature and supply voltage). Thus the macromodel is often not as exhaustive as the datasheet, its purpose is to illustrate the main parameters of the product.

Data derived from macromodels used outside of the specified conditions (for example, V_{CC} , temperature) or worse, outside of the device operating conditions (for example, V_{CC} , V_{icm}), are not reliable in any way.

[Section 4.2](#) provides the electrical characteristics resulting from the use of the TS922, TS922A macromodel.

4.2 Electrical characteristics from macromodelization

Table 5. Electrical characteristics resulting from macromodel simulation at $V_{CC} = 3\text{ V}$, $V_{CC-} = 0\text{ V}$, R_L , C_L connected to $V_{CC}/2$, $T_{amb} = 25\text{ °C}$ (unless otherwise specified)

Symbol	Conditions	Value	Unit
V_{io}		0	mV
A_{vd}	$R_L = 10\text{ k}\Omega$	200	V/mV
I_{CC}	No load, per operator	1.2	mA
V_{icm}		-0.2 to 3.2	V
V_{OH}	$R_L = 10\text{ k}\Omega$	2.95	
V_{OL}		25	mV
I_{sink}	$V_O = 3\text{ V}$	80	mA
I_{source}	$V_O = 0\text{ V}$		
GBP	$R_L = 600\text{ k}\Omega$	4	MHz
SR	$R_L = 10\text{ k}\Omega$, $C_L = 100\text{ pF}$	1.3	V/ μ s
ϕ_m	$R_L = 600\text{ k}\Omega$	68	Degrees

4.3 Macromodel code

```

** Standard Linear Ics Macromodels, 1996.
** CONNECTIONS:
* 1 INVERTING INPUT
* 2 NON-INVERTING INPUT
* 3 OUTPUT
* 4 POSITIVE POWER SUPPLY
* 5 NEGATIVE POWER SUPPLY
*
.SUBCKT TS92X 1 2 3 4 5
*
.MODEL MDTH D IS=1E-8 KF=2.664234E-16 CJO=10F
*
* INPUT STAGE
CIP 2 5 1.000000E-12
CIN 1 5 1.000000E-12
EIP 10 5 2 5 1
EIN 16 5 1 5 1
RIP 10 11 8.125000E+00
RIN 15 16 8.125000E+00
RIS 11 15 2.238465E+02
DIP 11 12 MDTH 400E-12
DIN 15 14 MDTH 400E-12
VOFP 12 13 DC 153.5u
VOFN 13 14 DC 0
IPOL 13 5 3.200000E-05
CPS 11 15 1e-9
DINN 17 13 MDTH 400E-12
VIN 17 5 -0.100000e+00
DINR 15 18 MDTH 400E-12
VIP 4 18 0.400000E+00
FCP 4 5 VOFP 1.865000E+02
FCN 5 4 VOFN 1.865000E+02
FIBP 2 5 VOFP 6.250000E-03
FIBN 5 1 VOFN 6.250000E-03
* GM1 STAGE *****
FGM1P 119 5 VOFP 1.1
FGM1N 119 5 VOFN 1.1
RAP 119 4 2.6E+06
RAN 119 5 2.6E+06
* GM2 STAGE *****
G2P 19 5 119 5 1.92E-02
G2N 19 5 119 4 1.92E-02
R2P 19 4 1E+07

```

```

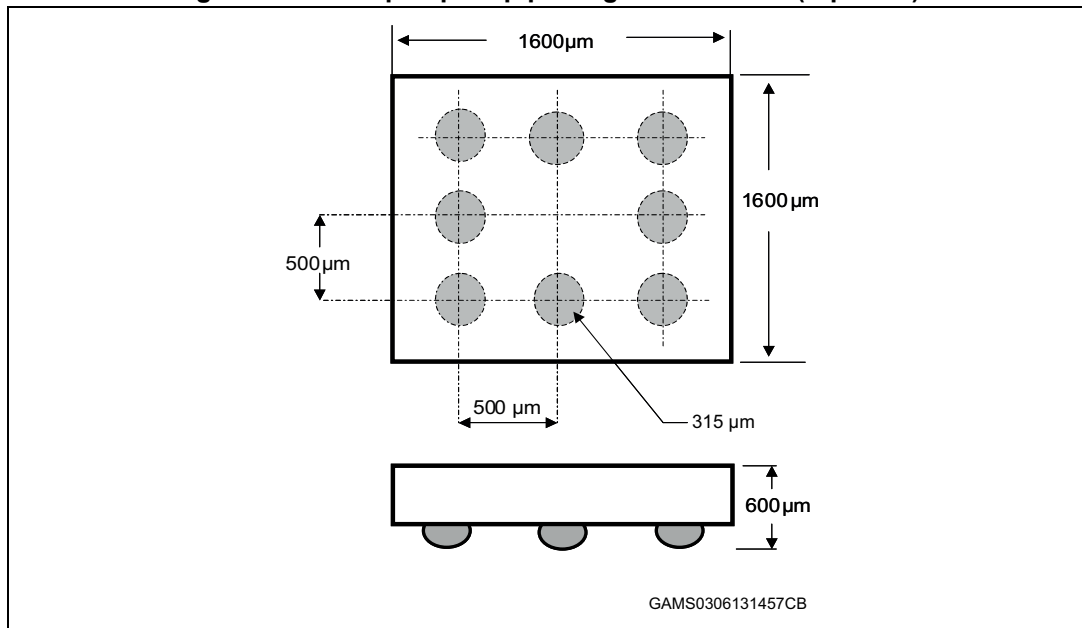
R2N 19 5 1E+07
*****
VINT1 500 0 5
GCONVP 500 501 119 4 19.38
VP 501 0 0
GCONVN 500 502 119 5 19.38
VN 502 0 0
***** orientation isink isource *****
VINT2 503 0 5
FCOPY 503 504 VOUT 1
DCOPYP 504 505 MDTH 400E-9
VCOPYP 505 0 0
DCOPYN 506 504 MDTH 400E-9
VCOPYN 0 506 0
*****
F2PP 19 5 poly(2) VCOPYP VP 0 0 0 0 0.5
F2PN 19 5 poly(2) VCOPYP VN 0 0 0 0 0.5
F2NP 19 5 poly(2) VCOPYN VP 0 0 0 0 1.75
F2NN 19 5 poly(2) VCOPYN VN 0 0 0 0 1.75
* COMPENSATION *****
CC 19 119 25p
* OUTPUT *****
DOPM 19 22 MDTH 400E-12
DONM 21 19 MDTH 400E-12
HOPM 22 28 VOUT 6.250000E+02
VIPM 28 4 5.000000E+01
HONM 21 27 VOUT 6.250000E+02
VINM 5 27 5.000000E+01
VOUT 3 23 0
ROUT 23 19 6
COUT 3 5 1.300000E-10
DOP 19 25 MDTH 400E-12
VOP 4 25 1.052
DON 24 19 MDTH 400E-12
VON 24 5 1.052
.ENDS;TS92X
    
```

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

5.1 8-bump Flip-chip package information

Figure 14. 8-bump Flip-chip package dimensions (top view)



- Die size: 1600 μm x 1600 μm ±30 μm
 Die height: 350 μm ±20 μm
 Die height (including bumps): 600 μm
 Bump diameter: 315 μm ±50 μm
 Bump height: 250 μm ±40 μm
 Pitch: 500 μm ±10 μm
 Backcoating

Table 6. 8-bump Flip-chip footprint recommendation

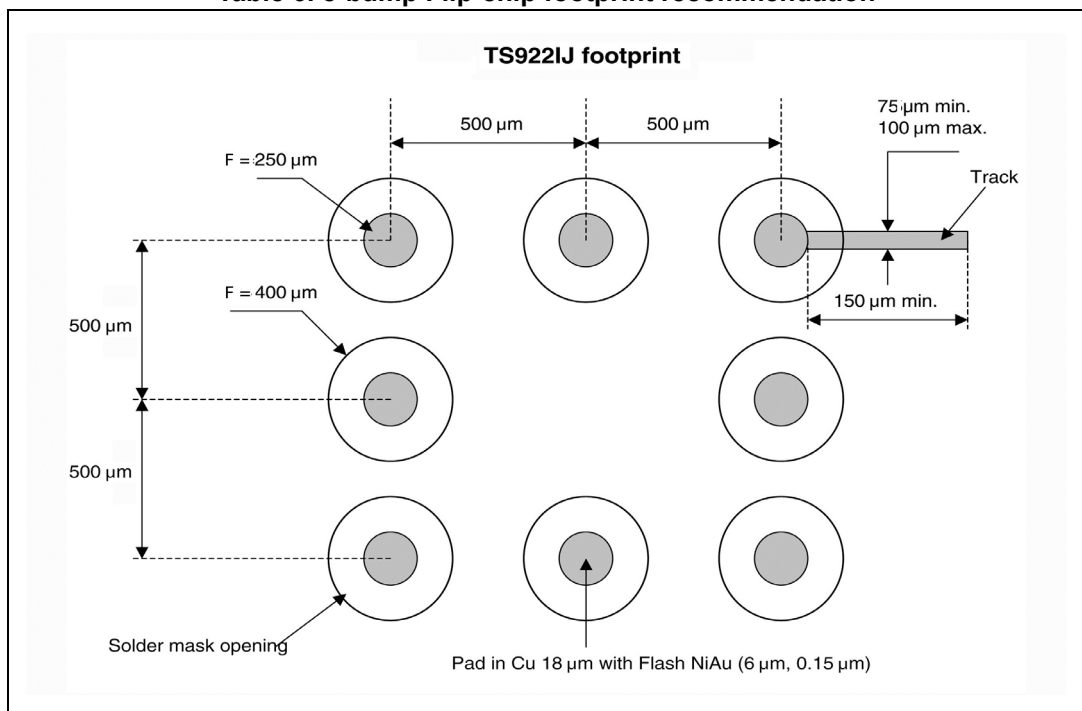
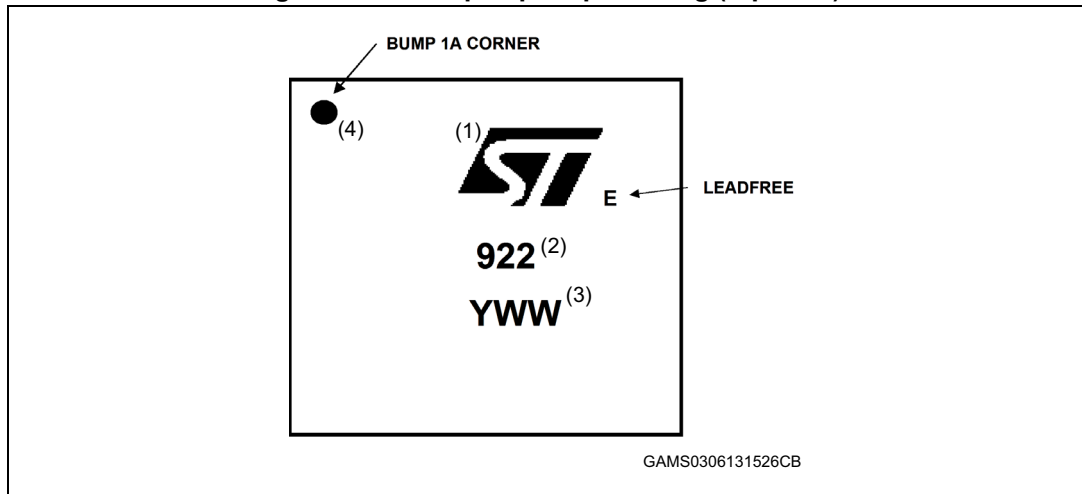
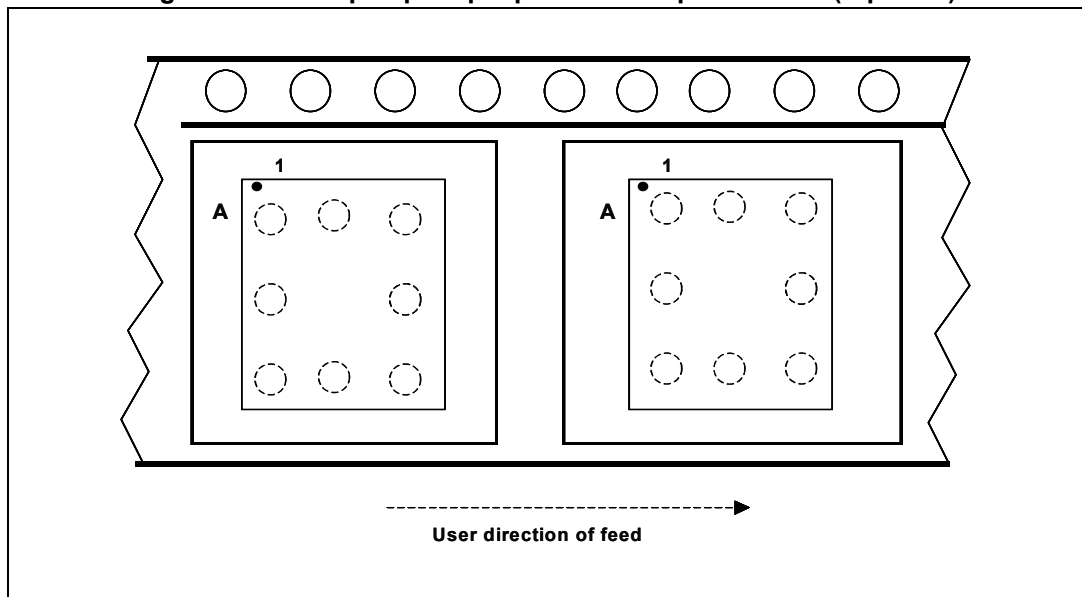


Figure 15. 8-bump Flip-chip marking (top view)



1. ST logo
2. Part number
3. Date code: Y = year, WW = week
4. This dot indicates the bump corner 1A

Figure 16. 8-bump Flip-chip tape and reel specification (top view)



1. Device orientation: the devices are oriented in the carrier pocket with bump number A1 adjacent to the sprocket holes.

5.2 MiniSO8 package information

Figure 17. MiniSO8 package mechanical drawing

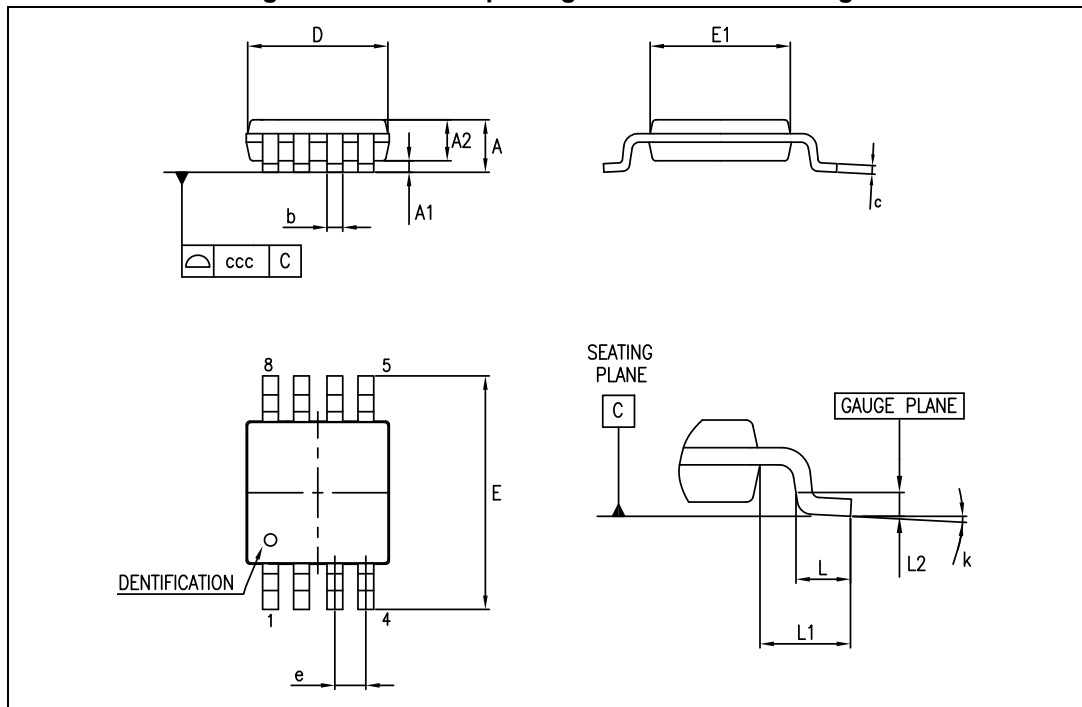


Table 7. MiniSO8 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.1			0.043
A1	0		0.15	0		0.006
A2	0.75	0.85	0.95	0.030	0.033	0.037
b	0.22		0.40	0.009		0.016
c	0.08		0.23	0.003		0.009
D	2.80	3.00	3.20	0.11	0.118	0.126
E	4.65	4.90	5.15	0.183	0.193	0.203
E1	2.80	3.00	3.10	0.11	0.118	0.122
e		0.65			0.026	
L	0.40	0.60	0.80	0.016	0.024	0.031
L1		0.95			0.037	
L2		0.25			0.010	
k	0°		8°	0°		8°
ccc			0.10			0.004

5.3 SO8 package information

Figure 18. SO8 package mechanical drawing

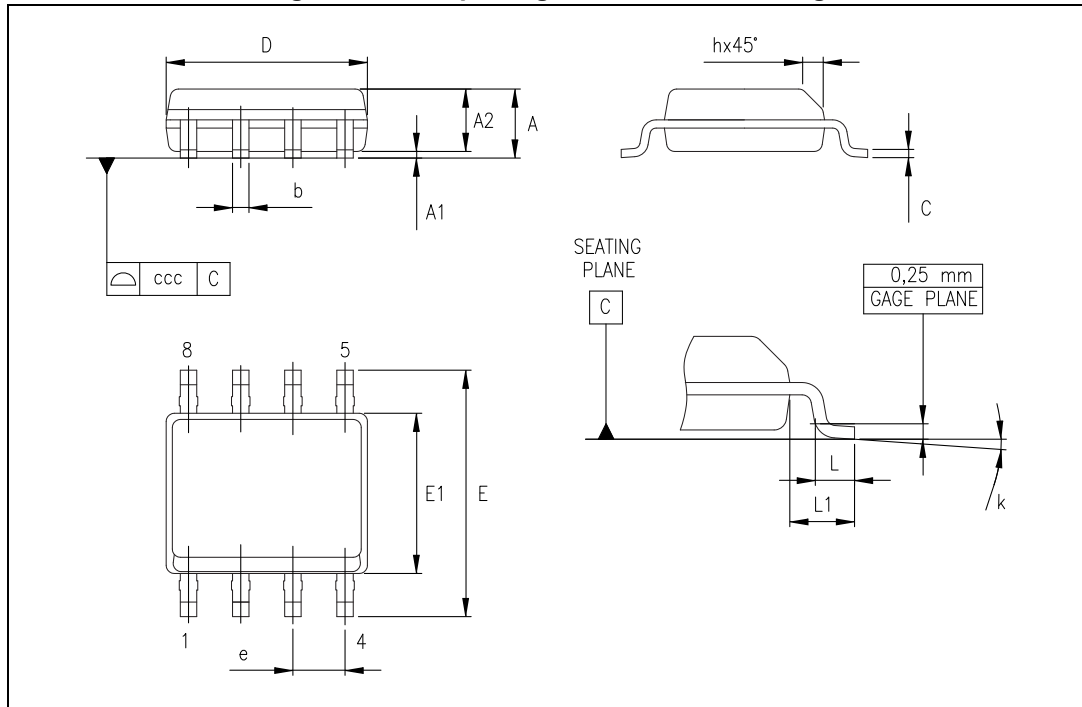


Table 8. SO8 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.069
A1	0.10		0.25	0.004		0.010
A2	1.25			0.049		
b	0.28		0.48	0.011		0.019
c	0.17		0.23	0.007		0.010
D	4.80	4.90	5.00	0.189	0.193	0.197
E	5.80	6.00	6.20	0.228	0.236	0.244
E1	3.80	3.90	4.00	0.150	0.154	0.157
e		1.27			0.050	
h	0.25		0.50	0.010		0.020
L	0.40		1.27	0.016		0.050
L1		1.04			0.040	
k	0		8°	1°		8°
ccc			0.10			0.004

5.4 TSSOP8 package information

Figure 19. TSSOP8 package mechanical drawing

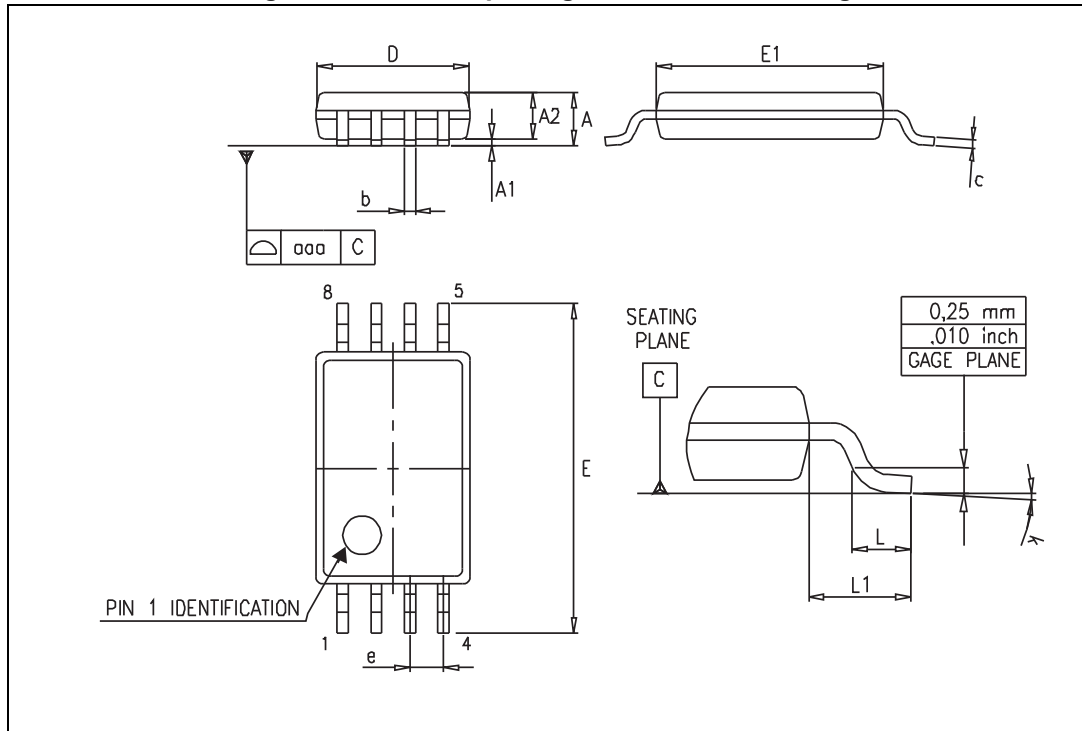


Table 9. TSSOP8 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.20			0.047
A1	0.05		0.15	0.002		0.006
A2	0.80	1.00	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.008
D	2.90	3.00	3.10	0.114	0.118	0.122
E	6.20	6.40	6.60	0.244	0.252	0.260
E1	4.30	4.40	4.50	0.169	0.173	0.177
e		0.65			0.0256	
k	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030
L1		1			0.039	
aaa			0.10			0.004

5.5 DIP8 package information

Figure 20. DIP8 package mechanical drawing

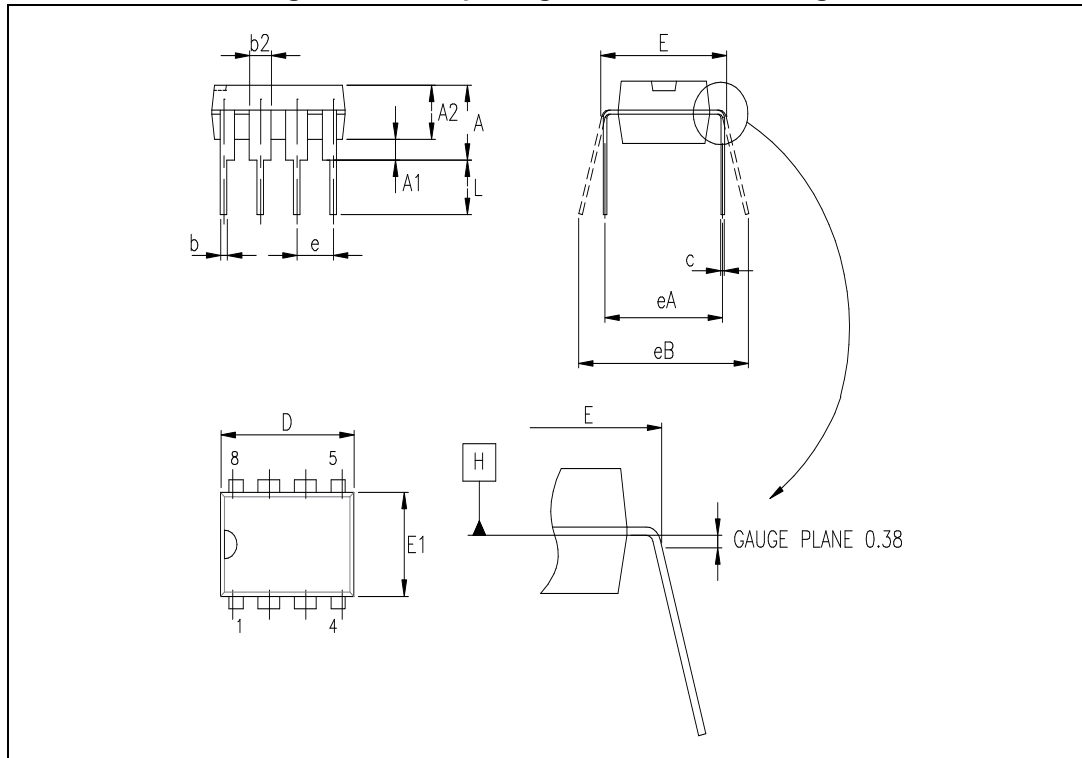


Table 10. DIP8 package mechanical data

Symbol	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			5.33			0.210
A1	0.38			0.015		
A2	2.92	3.30	4.95	0.115	0.130	0.195
b	0.36	0.46	0.56	0.014	0.018	0.022
b2	1.14	1.52	1.78	0.045	0.060	0.070
c	0.20	0.25	0.36	0.008	0.010	0.014
D	9.02	9.27	10.16	0.355	0.365	0.400
E	7.62	7.87	8.26	0.300	0.310	0.325
E1	6.10	6.35	7.11	0.240	0.250	0.280
e		2.54			0.100	
eA		7.62			0.300	
eB			10.92			0.430
L	2.92	3.30	3.81	0.115	0.130	0.150

6 Ordering information

Table 11. Order codes

Order codes	Temperature range	Package	Packaging	Marking
TS922ID TS922IDT	-40 °C to +125 °C	SO-8	Tube or tape and reel	922I
TS922AID TS922AIDT				922AI
TS922IYDT ⁽¹⁾ TS922AIYDT ⁽¹⁾				922IY 922AIY
TS922IPT TS922AIPT		TSSOP8	Tape and reel	922I 922AI
TS922IST TS922AIST		MiniSO8		K158 K159
TS922IN		DIP8		Tube
TS922IYPT ⁽²⁾ TS922AIYPT ⁽²⁾		TSSOP8 (automotive grade)	Tape and reel	922IY 922AY
TS922IYST ⁽²⁾ TS922AIYST ⁽²⁾		MiniSO8 (automotive grade)		K10A K10B
TS922IJT/EIJT		Flip-chip with backcoating		922

1. Qualified and characterized according to AEC Q100 and Q003 or equivalent, advanced screening according to AEC Q001 and Q 002 or equivalent.
2. Qualification and characterization according to AEC Q100 and Q003 or equivalent, advanced screening according to AEC Q001 and Q 002 or equivalent are ongoing.

7 Revision history

Table 12. Document revision history

Date	Revision	Changes
01-Feb-2001	1	First release.
01-Jul-2004	2	Flip-chip package inserted in the document.
02-May-2005	3	Modifications in AMR Table 1 on page 4 (explanation of V_{id} and V_i limits, ESD MM and CDM values added, R_{thja} added).
01-Aug-2005	4	PPAP references inserted in the datasheet, see Table 6 on page 22 .
01-Mar-2006	5	TS922EIJT part number inserted in the datasheet, see Table 6 on page 22 .
26-Jan-2007	6	Modifications in AMR Table 1 on page 4 (R_{thjc} added), parameter limits on full temperature range added in Table 3 on page 6 and Table 4 on page 8 .
12-Nov-2007	7	Added notes on ESD in AMR table. Re-formatted package information. Added notes for automotive grade in order codes table.
02-Feb-2010	8	Document reformatted. Added root part number TS922A on cover page. Removed TS922AIYD order code from Table 11 .
15-Jan-2013	9	Added MiniSO8 package. Modified test conditions for CMR in Table 3 and Table 4 . Replaced V_{DD} by V_{CC} in title of Table 3 , Table 4 , and Table 5 . Updated titles of Figure 7 to Figure 12 (added conditions to differentiate them). Removed TS922IYD device from Table 11 . Minor corrections throughout document.
04-Jun-2013	10	Features : updated package information for Flip-chip Figure 2 : Updated title Table 1 : updated footnotes 5 , 6 , and 7 Table 3 and Table 4 : replaced DV_{io} with $\Delta V_{io}/\Delta T$ Figure 14 : added backcoating to package information Figure 15 : updated footnote 3 Table 11 : updated package information for Flip-chip

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT AUTHORIZED FOR USE IN WEAPONS. NOR ARE ST PRODUCTS DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2013 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com